



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Features

- Compliant with AEC-Q200 Rev-C - Stress Test Qualification for Passive Components in Automotive Applications
- Small footprint size (1210)
- Operating temperature range up to 125 °C
- Low thermal derating factor
- Higher hold currents at elevated temperatures

■ RoHS compliant*

■ Agency recognition:  

MF-USHT Series - PTC Resettable Fuses

Electrical Characteristics

Model	V max. Volts	I max. Amps	I _{hold}	I _{trip}	Resistance		Max. Time To Trip		Tripped Power Dissipation
			Amperes at 23 °C		Ohms at 23 °C		Amperes at 23 °C	Seconds at 23 °C	Watts at 23 °C
			Hold	Trip	R _{Min.}	R _{1Max.} **			Typ.
MF-USHT035KX	30	20	0.35	1.75	0.4	2.2	8.0	0.1	1.0
MF-USHT050KX	30	20	0.50	2.50	0.3	1.6	8.0	0.1	1.0

**R_{1Max.} measured 24 hours post reflow.

Environmental Characteristics

Operating Temperature.....	-40 °C to +125 °C	
Passive Aging.....	+125 °C, 1000 hours.....	R _{final} < R _{1max}
Humidity Aging.....	+85 °C, 85 % R.H. 1000 hours.....	R _{final} < R _{1max}
Thermal Shock.....	+125 °C to -40 °C, 20 times.....	R _{final} < R _{1max}
Solvent Resistance.....	MIL-STD-202, Method 215.....	No change
Vibration.....	MIL-STD-883C, Method 2007.1,.....	No change
	Condition A	
Moisture Sensitivity Level (MSL).....	Level 1	
ESD Classification - HBM.....	Class 6	

Test Procedures And Requirements For Model MF-USHT Series

Test	Test Conditions	Accept/Reject Criteria
Visual/Mech.....	Verify dimensions and materials.....	Per MF physical description
Resistance.....	In still air @ 23 °C.....	R _{min} ≤ R ≤ R _{1max}
Time to Trip.....	At specified current, V _{max} , 23 °C.....	T ≤ max. time to trip (seconds)
Hold Current.....	30 min. at I _{hold}	No trip
Trip Cycle Life.....	V _{max} , I _{max} , 100 cycles.....	No arcing or burning
Trip Endurance.....	V _{max} , 48 hours.....	No arcing or burning
Solderability.....	ANSI/J-STD-002.....	95 % min. coverage
cUL File Number.....	E174545 http://www.ul.com/ Follow link to Online Certificates Directory, then enter UL File No. E174545, or click here	
TÜV Certificate.....	Certificate Number Available on Request, or click here	

Thermal Derating Chart - I_{hold} (Amps)

Model	Ambient Operating Temperature									
	-40 °C	-20 °C	0 °C	+23 °C	+40 °C	+50 °C	+60 °C	+70 °C	+85 °C	+125 °C
MF-USHT035KX	0.508	0.459	0.406	0.350	0.308	0.284	0.259	0.235	0.196	0.095
MF-USHT050KX	0.725	0.655	0.580	0.500	0.440	0.405	0.370	0.335	0.280	0.135

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

Applications

- Protection of automotive circuitry including engine control modules
- Overcurrent surge protection of electronic equipment required to operate at high operating temperature ranges
- Resettable fault protection for general electronic equipment

MF-USHT Series - PTC Resettable Fuses

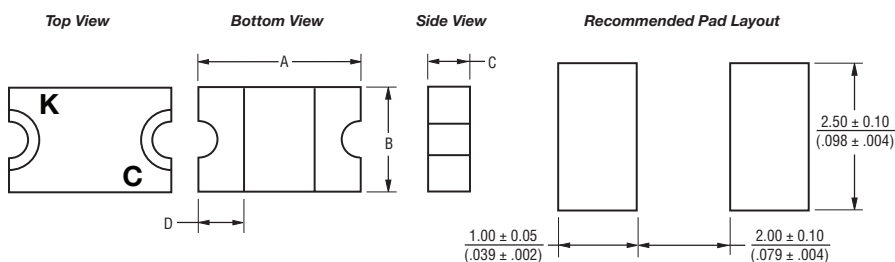
BOURNS®

Product Dimensions

Model	A		B		C		D
	Min.	Max.	Min.	Max.	Min.	Max.	Min.
MF-USHT035X	$\frac{3.00}{(0.118)}$	$\frac{3.43}{(0.135)}$	$\frac{2.35}{(0.093)}$	$\frac{2.80}{(0.110)}$	$\frac{0.40}{(0.016)}$	$\frac{0.85}{(0.033)}$	$\frac{0.30}{(0.012)}$
MF-USHT050X	$\frac{3.00}{(0.118)}$	$\frac{3.43}{(0.135)}$	$\frac{2.35}{(0.093)}$	$\frac{2.80}{(0.110)}$	$\frac{0.40}{(0.016)}$	$\frac{0.85}{(0.033)}$	$\frac{0.30}{(0.012)}$

Packaging: 3000 pcs. per reel.

DIMENSIONS: $\frac{\text{MM}}{(\text{INCHES})}$



Terminal material:

Nickel/gold plated.

Termination pad solderability:

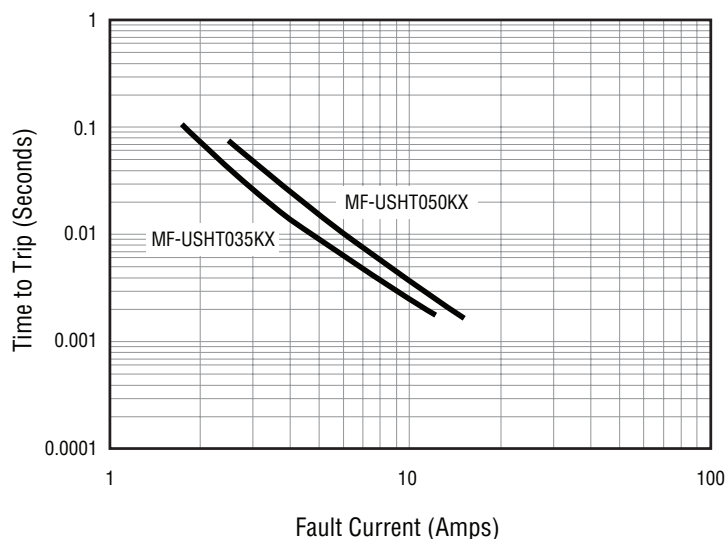
Standard Au finish:

Meets ANSI/J-STD-002 Category 2.

Recommended Storage:

40 °C max./70 % RH max.

Typical Time to Trip at 23 °C



The Time to Trip curves represent typical performance of a device in a simulated application environment. Actual performance in specific customer applications may differ from these values due to the influence of other variables.

How to Order

MF - USHT 035 K X - 2

Multifuse® Product Designator _____

Series _____

USHT = 1210 High Temperature Surface Mount Component

Hold Current, I_{hold} _____

035 - 050 (0.35 - 0.50 Amps)

Material Specific Code _____

Multifuse® freeXpansion™ Design _____

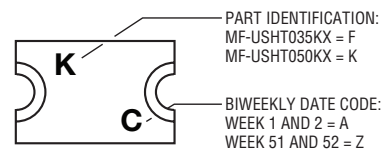
Packaging _____

Packaged per EIA 481-1

-2 = Tape and Reel

Typical Part Marking

Represents total content. Layout may vary.



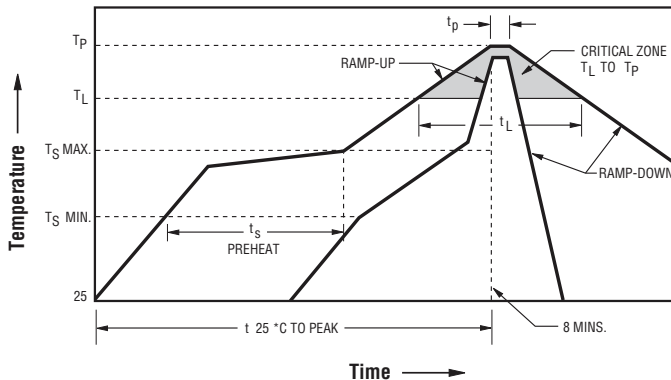
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MF-USHT Series - PTC Resettable Fuses

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Solder Reflow Recommendations



Notes:

- MF-USHT models cannot be wave soldered or hand soldered. Please contact Bourns for soldering recommendations.
- All temperatures refer to topside of the package, measured on the package body surface.
- If reflow temperatures exceed the recommended profile, devices may not meet the published specifications.
- Compatible with Pb and Pb-free solder reflow profiles.
- Excess solder may cause a short circuit, especially during hand soldering. Please refer to the Multifuse® Polymer PTC Soldering Recommendation guidelines.
- Designed for single solder reflow operations.

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (TS _{max} to TP)	3 °C / second max.
PREHEAT: Temperature Min. (TS _{min}) Temperature Max. (TS _{max}) Time (ts _{min} to ts _{max})	150 °C 200 °C 60~180 seconds
TIME MAINTAINED ABOVE: Temperature (TL) Time (tL)	217 °C 60~150 seconds
Peak / Classification Temperature (TP)	260 °C
Time within 5 °C of Actual Peak Temperature (tp)	20~40 seconds
Ramp-Down Rate	6 °C / second max.
Time within 25 °C to Peak Temperature	8 minutes max.

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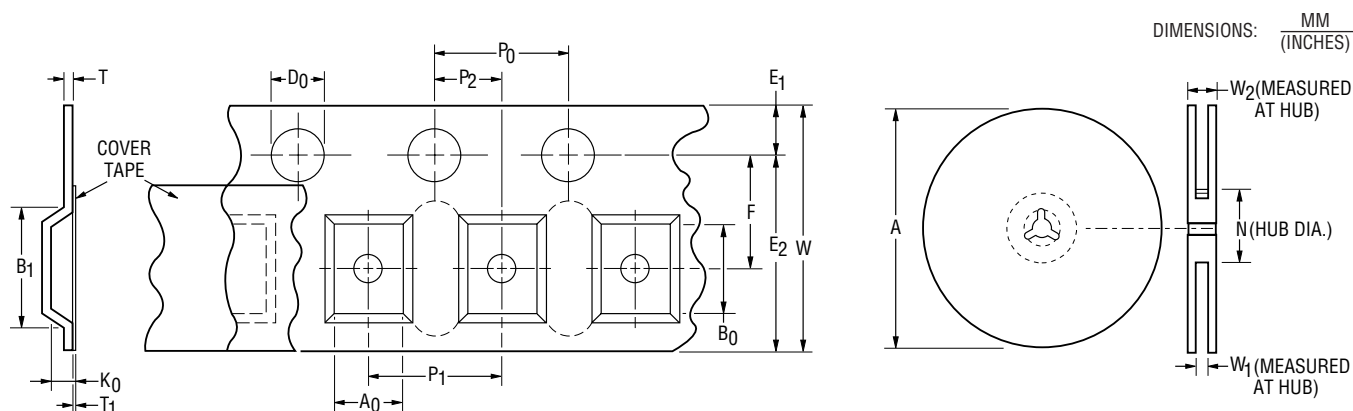
The Americas: Tel: +1-951 781-5500 • Email: americus@bourns.com

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MF-USHT Series Tape and Reel Specifications

BOURNS®

Tape Dimensions		MF-USHT Series per EIA 481-1
W		8.0 ± 0.30 (0.315 \pm 0.012)
P ₀		4.0 ± 0.10 (0.157 \pm 0.004)
P ₁		4.0 ± 0.10 (0.157 \pm 0.004)
P ₂		2.0 ± 0.05 (0.079 \pm 0.002)
A ₀		3.00 ± 0.10 (0.118 \pm 0.004)
B ₀		3.65 ± 0.10 (0.144 \pm 0.004)
B ₁ max.		4.35 (0.171)
D ₀		$1.5 + 0.10/-0.0$ (0.059 + 0.004/-0)
F		3.5 ± 0.05 (0.138 \pm 0.002)
E ₁		1.75 ± 0.10 (0.069 \pm 0.004)
E ₂ min.		6.25 (0.246)
T max.		0.6 (0.024)
T ₁ max.		0.1 (0.004)
K ₀		0.85 ± 0.10 (0.033 \pm 0.004)
Leader min.		390 (15.35)
Trailer min.		160 (6.30)
Reel Dimensions		
A max.		185 (7.28)
N min.		50 (1.97)
W ₁		$8.4 + 1.5/-0.0$ (0.331 + 0.059/-0.0)
W ₂ max.		14.4 (0.567)



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